Amdt. dated January 12, 2005

Reply to Office Action of November 3, 2004

This listing of claims replaces all prior versions, and listings of claims in the instant application:

Listing of Claims:

 (Currently amended) The structure as claimed in Claim 3,

wherein the substrate comprises comprising a lead frame; and the unsymmetrical part comprises a gate,

the clamp comprising:

a window formed to expose upward a die mounted on a die pad of the lead frame and leads on an outer circumference of the die on a heater block during a wire bonding process; and

at least one or more observation holes comprising the observation hole, the at least one or more observation holes formed in an outer circumference of the window to set the gate of the lead frame within a lead eye box and a lead eye point.

- 2. (Previously presented) The structure as claimed in claim 1, wherein the at least one or more observation holes are located in opposite positions of the outer circumference of the window to detect an orientation not only of a normal lead frame but also of an inverted lead frame.
- 3. (Currently amended) A structure comprising:

 a substrate comprising an unsymmetrical part selected
 from the group consisting of a dent part of a gate and a
 plated layer on a gate; and

a clamp, the unsymmetrical part being visible through an observation hole of the clamp.

4-5. (Canceled)

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6. (Currently amended) The structure as claimed in claim [[5]] 3 wherein the plated layer comprises a material selected from the group consisting of aluminum, silver, gold, palladium, nickel, lead, and tin alloys.

7. (Canceled)

- 8. (Original) The structure as claimed in claim 3 wherein the substrate further comprises a support bar.
- 9. (Original) The structure as claimed in claim 3 further comprising a camera for setting a lead eye box and a lead eye point on the unsymmetrical part.
- 10. (Original) The structure as claimed in claim 3 wherein the substrate comprises a normal lead frame.
- 11. (Original) The structure as claimed in claim 3 wherein the substrate comprises an inverted lead frame.
- 12. (Original) The structure as claimed in claim 3 wherein the substrate is selected from the group consisting of a lead frame, a printed circuit board, a circuit film, and a circuit tape.
- 13. (Original) The structure as claimed in claim 3 further comprising a die exposed through a window of the clamp.
- 14. (Original) The structure as claimed in claim 13 wherein leads of the substrate are exposed through the window of the clamp.

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- 15. (Original) The structure as claimed in claim 13 wherein the die is a symmetrical die.
- 16. (Original) The structure as claimed in claim 13 wherein the die comprises a specific pattern.
 - 17-26. (Canceled.)
 - 27. (Currently amended) A structure comprising:
 - a lead frame comprising:
 - a gate an unsymmetrical part selected from the group consisting of a dent part of a gate and a plated layer on a gate;
 - a support bar; and
 - a die pad;
 - a die mounted on the die pad;
 - a clamp comprising:
 - a window, the die being exposed through the window; and
 - an observation hole, the <u>gate unsymmetrical part</u> being exposed through the observation hole, wherein the support bar is located on an outer circumference of the clamp.
- 28. (Previously presented) The structure as claimed in claim 27 wherein the die comprises a specific pattern.
 - 29. (Currently amended) A structure comprising:
- a leadframe comprising a gate an unsymmetrical part selected from the group consisting of a dent part of a gate and a plated layer on a gate; and
 - a clamp comprising:

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a window formed to expose upward a die mounted on a die pad of the lead frame and leads on an outer circumference of the die; and

an observation hole formed to set the gate unsymmetrical part of the lead frame within a lead eye box and a lead eye point.

30. (Canceled)

- 31. (New) The structure as claimed in Claim 16 wherein the specific pattern is adjacent an edge of the die and located outside of bond pads of the die.
- 32. (New) The structure as claimed in Claim 3 wherein the clamp comprises:
- a window formed to expose upward a die mounted on a die pad of the substrate and leads on an outer circumference of the die; and

two observation holes comprising the observation hole.

- 33. (New) The structure as claimed in Claim 3 wherein the substrate further comprises a support bar, the structure further comprising:
- a first lead eye box and a first lead eye point on the unsymmetrical part of the substrate and a second lead eye box and a second lead eye point on the support bar of the substrate.